

high reliability discrete semiconductor up-screening Q4-2020



www.centralsemi.com

vision statement

we aspire to be the preferred manufacturer of the most innovative discrete semiconductor solutions in the industry

core values

purpose

Customer satisfaction is our passion.

innovation

Overcome challenges through creative solutions.

enthusiasm

The resolve to achieve excellence.

trust Empower to succeed

teamwork

Results through dynamic collaboration.

heritage Exceptional past, exciting future.



Your Trusted Source for over 46 years



Discretes do Matter[™]

A Heritage of Success

An outstanding reputation:

Since 1974, Central Semiconductor has manufactured innovative discrete semiconductors for OEM products worldwide. Devices are available in surface mount, through-hole and bare die. Epoxy molded, glass passivated, and hermetically sealed packages are available for a broad range of device types. Central maintains ISO 9001:2015 certification.

Devices include:

- Small signal transistors
- Bipolar power transistors
- MOSFETs/JFETs
- EOS protection devices (TVS)
- Diodes/Rectifiers
- Thyristors
- Multi Discrete Modules (MDM[™]



Central Semiconductor has the capability to screen COTS devices to a variety of standards.





A Heritage of Success

The highest quality and reliability:

To ensure devices meet the highest quality expectations, Central is an ISO9001:2008 certified manufacturer, currently transitioning to ISO9001:2015. Our devices are RoHS2 and REACH compliant with quality data readily available from our website.

Our ongoing commitment:

Central Semiconductor is committed to designing and manufacturing innovative quality products, and delivering on time, with outstanding service and support, at competitive prices. Our team is driven to exceed customers' expectations. We appreciate your support and partnership in helping to realize our mutual objectives.





High Reliability Devices

Bare Die

Central has the capability to perform the majority of up-screen testing in-house.



MIL-PRF 38534 (Class H and K equivalent) MIL-PRF-19500 (Class HC and KC equivalent)

- 100% of die inventory is held in the U.S.
- 100% of Class H equivalent testing is performed in-house
- Customer-specific up-screening

Packaged Devices

Central Semiconductor has the capability to up-screen COTS devices to meet customers' requirements.





MIL-PRF-19500

- EX devices provide up-screening to JANTX equivalents
- J-Lite and JX-Lite up-screening is available with modified test flows
- Customer-specific up-screening



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Baseline: Broad Range of Standard Products

- Small Signal Transistors
 - Low V_{CE(SAT)}
 - General Purpose Amplifier/Switch
 - High Current/High Voltage
 - Low Noise
 - Darlington
 - RF Oscillator
 - Chopper
- Bipolar Power Transistors
 - Low V_{CE(SAT)}
 - General Purpose Amplifier/Switch
 - High/ Extremely High Voltage
 - Darlington
- MOSFETs
 - 20V 800V, 100mA 12A
 Single and Dual N-Channel &
 P-Channel Enhancement-mode
- Thyristors
 - Triacs, Diacs, SCRs



- Diodes
 - Fast Switching
 - Schottky
 - Low and Ultra Low Leakage
 - Zener, and TC Zener
 - Current Limiting
- Rectifiers
 - General Purpose, Fast, Super Fast, UltraFast and HyperFast Recovery
 - Schottky
 - Bridge
- Protection Devices
 - Transient Voltage Suppressors
- Silicon Carbide Devices
 - Schottky Rectifiers, Bare Die
- Multi Discrete Module (MDM™)
 - MOSFET/Rectifier combinations
 - Transistor/Rectifier combinations



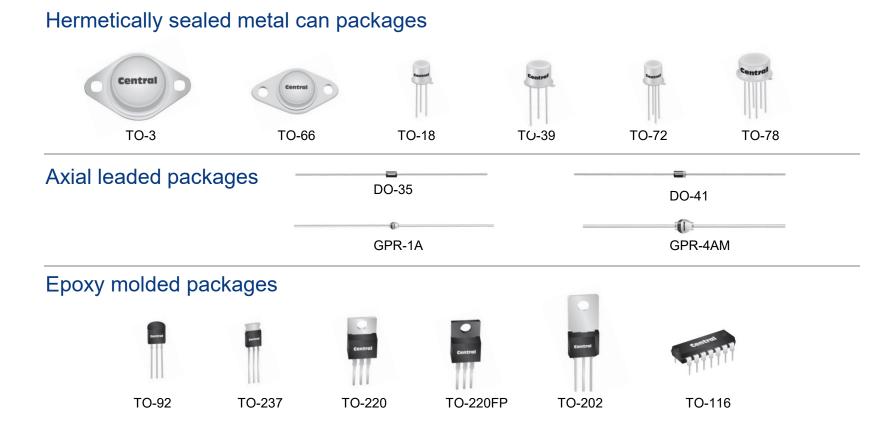
Extensive Range of SMD Package Options

> 1.0mm	Profile -					he large I can sa				•					
Central			control	Contrast	5555		Cent	trai []			0			Cancer	
D²PAK 16.6 x 10.4 x 4.8	DPAK 10.4 x 6.73 x 2.38	DPAK-2L 10.62 x 6.86 x 2.54	SMDIP 8.51 x 10.41 x 2.49	LPDIP 6.7 x 5.15 x 1.45	SOI 6.18 x x 1.	5.01 4.9 x	7.0 8.13 x	6.22	5.59	MB x 3.81 2.44	5.5	x 3.7 5.5	SMA i9 x 2.92 x 2.62	SMAF 4.9 x 2. x 1.1	
	S										(•			
SOT-89 4.7 x 4.5 x 1.7	SOT-26 3.0 x 3.0 x 1.2	SOT-143 3.04 x 2.50 x 1.14	SOD-12 3.9 x 1.8 x 1.35		1.95	SOT-23 3.05 x 2.49 x 1.09	SOT-23F 3.00 x 2.50 x 1.0		SOT-36 2.2 x 2. x 1.1		SOT-: 2.2 x 2 x 1.	2.2 2	OD-323 .6 x 1.35 x 1.0	6.65 x	M364 5 x 4.35 1.2 pm View)
< 1.0mm	n Profile														
•	• •	~	0	0	4	4	47	4	3	1		633			
1.45 x 0.65 1.7	T-543 SOT-563 x 1.7 1.7 x 1.7 0.6 x 0.6	SOT-523 1.7 x 1.7 x 0.78		.80 x 0.9 1.9	0-323FL 5 x 1.4 0.85	TLM621 2.15 x 1.15 x 0.8 (Bottom View)	TLM322S 2.05 x 2.05 x 0.6 (Bottom View)	3.1 x	1532 x 2.1 1.0 m View)	TLM83 3.1 x 2 x 1.0 (Bottom V	.1	TLM832DS 3.05 x 2.05 x 1.0 (Bottom View	3.1 x 3 x 1.0	.1	DD-123FL 3.7 x 1.7 x 0.8
< 0.5mm	n Profile														
TLM2D3D6 0.65 x 0.35 x 0.32 (Bottom View)	TLM3D 0.85 x 0 x 0.4 (Bottom \	0.65	* SOD-882L 1.05 x 0.65 x 0.4 (Bottom View)	SOT-88 1.05 x 0 x 0.4 (Bottom \	.65	SOD-923 1.10 x 0.65 x 0.41	1.1	0T-923 0 x 0.65 2 0.41		* SOT- 1.05 x x 0.	1.05	1.0	OT-963 5 x 1.05 x 0.5	2	CLM621H .15 x 1.65 x 0.4 iottom View)





Extensive Range of Through-hole Package Options







Ideal Solutions for High Reliability requirements

Markets:

- Military
- Medical
- Aerospace
- Industrial



Zener diodes





Applications: Avionics & Comms. Equipment

Central's up-screened products are ideal for the most demanding avionics and communications applications:

- Aircraft control boards
- Radar systems
- Passive optical networks (GPON, EPON)
- Transceiver equipment
- Cabin entertainment and communications systems

















Testing capabilities:



Thermal stream testing



Burn-in testing



Scanning Electron Microscopy (SEM)

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Temperature cycle testing



High temperature & humidity testing



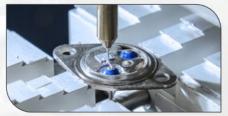
Highly-accelerated stress testing (HAST)



Particle Impact Noise Detection (PIND)



Fine leak testing



Wire pull & die shear testing

All tests performed to **MII -STD-750** test methods. Central provides dependable management of the work flow with accurate device identification throughout the process.



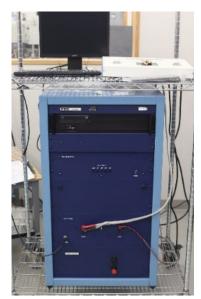


Testing capabilities:



X-Ray

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Multiple waveform surge tester



One Box test chambers



C-SAM



PIND Tester



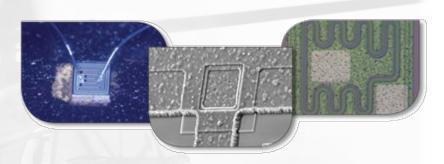
De-cap station





Quality by Design

Central's designs provide superior performance and reliability by using superior materials in the construction of devices. Central's devices meet or exceed commercial performance standards and outperform industry expectations.



Benefits:

- Deal directly with Central Semiconductor
- Single point of contact from development through test
- Commitment to on-time delivery
- Receptive to custom test requirements





Fast, thorough quoting process

Central Semiconductor has made the quote process easy:

- 1) Contact your Central Sales representative or call 631-435-1110.
- 2) You will receive a quote within 1 to 5 business days.

(complex requests may take longer)

Attention to every detail is Central's highest concern. Central is committed to exceeding your expectations and earning your business on every order.





MIL-P	RF-3	853	4 Evaluation Elements			
Sub			Test	MIL	STD-883	Acceptance
Group			1 Test	Method	Conditions	Quantity
1	Х	X	Element electrical			100%
2	Х	X	Visual Inspection	2010		100%
				<u>1/2069</u>		
				<u>1/2070</u>		
				<u>1/2072</u>		
				<u>1/2073</u>		
3	Х	X	Internal visual	2010		10 (0)
				<u>1</u> /2069		
				<u>1/2070</u>		
				<u>1/2072</u>		
				1/2073		
4	Х		Temperature Cycling	1010	С	<u>2/ 10 (0)</u>
	Х		Mechanical shock or	2002	B, Y1 direction	_
			Constant Acceleration	2001	3,000 g's, Y1 direction	
	Х		Interim electrical			
	х		Burn-in	1015	240 hours	
					minimum at	
					+125°C	
	Х		Post burn-in electrical			
	Х		Steady-state life	1005		
	Х	X	Final electrical			
5	Х	X	Wire bond evaluation	2011		10 (0) wires or
						20 (1) wires
6	Х		SEM	2018		See method 2018
				<u>1</u> /2077		of MIL-STD-883 or
						method 2077 of
						MIL-STD-750

1/ MIL-STD-750 methods.

2/ A minimum of 10 die per wafer lot. For Class K, this quantity must contain 3 die from each wafer evaluated.



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MIL-PRF-19500

Typical bare die up-screening process for MIL-PRF-19500

MIL-PRF-19500 Evaluation Elements									
Sub	Class		Test	M	IL-STD-750	Acceptance			
Group	KC	HC	Test	Method	Conditions	Quantity			
1	Х	Х	Electrical test			100%			
2	X	X	Visual inspection	2069		100%			
				2070					
				2072					
				2073					
3A	Х	Х	Internal/die visual inspection	2069		45 (0) for			
				2070		class KC,			
				2072		22 (0) for			
				2073		class HC			
3B	X	X	Sample assembly			45 pieces min			
						for class KC,			
						22 pieces min			
						for class HC			



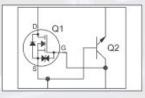
4						45 (0) for class KC,
						22 (0) for class HC
	x	x	Temperature cycling	1051	с	01355110
	x		Mechanical shock or Constant acceleration	2016 2006	Y1 axis direction Y1 axis direction	
	x	x	Electrical test (read/record)		Group A, subgroups 2, 3, 4	
	x	x	HTRB		Screen 10	
	x	x	Electrical test (read/record)	_	Group A, subgroup 2	
	x	x	Burn-in		Screen 12	
	x	x	Electrical test (read/record)		Group A, subgroups 2, 3	Subgroup 3 applies to class KC only
	x		Steady-state life			
			Transistors	1039	В	
			Power FETs	1042	A	
			Diodes/rectifiers	1038	A or B	
	x		Electrical test (read/record)		Group A, subgroups 2, 3, 4	
5A	x	x	Wire bond evaluation	2037	As applicable	22 (0) wires or 38 (1) wires
5B	x	x	Die shear evaluation	2017		5 (0) or 10 (1)
6	x		SEM	2077	As applicable	See test method 2077
7			RHA			Sample size
	X		Total dose	1019		per the
	x	-	Neutron irradiation	1017	-	specification sheet





Custom High Reliability Solutions

Your vision is our mission. Central excels at listening to customers' challenges and designing custom solutions that other manufacturers have no interest in pursuing. Just ask.



Standard options include:

- Electrical parameter screening
- Custom wafer diffusion and metallization
- Standard/customer-specific testing and up-screening



Super Industrial[™] solutions include:

- Customer-specific high reliability testing
- Custom interconnect
- Custom packaging



Spacellite[™] solutions:

- · Designed to function effectively in the harsh environment of space
- Specialized testing to insure reliability and lower cost
- Ideal for low Earth orbit (LEO) applications





Part numbering:

MIL-PRF-19500 and MIL-PRF-38534 Equivalents

Die:

H = MIL-PRF-38534 Class H equivalent (Ex: CP318V-H2N5682-CM)
K = MIL-PRF-38534 Class K equivalent (Ex: CP318V-K2N5682-CM)
HC = MIL-PRF-38534 Class H equivalent (Ex: CP318V-HC2N5682-CM)
KC = MIL-PRF-38534 Class H equivalent (Ex: CP318V-KC2N5682-CM)

JANTX equivalent:

EX = MIL-PRF-19500 equivalent (Ex: EX2N2222A)

J-Lite / JX-Lite: JL = J-Lite test flow JXL = JX-Lite test flow

Customer Specified:

CEN1234 = Customer specified custom test flow





Up-screening Guide

Scan this QR Code to download the brochure in PDF format



or visit:

https://www.centralsemi.com/upscreeningpdf

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